

Please amend claim 21 as follows:

21 (Amended). A method of connecting multiple semiconductor dies having bonding pads and a single leadframe having lead fingers, comprising:

D2
locating a first semiconductor die on the lead fingers of the leadframe;
stacking a second semiconductor die on said first semiconductor die; and
electrically connecting the bonding pads of the semiconductor dies to the same

lead fingers of the leadframe.

REMARKS

All of the pending claims were rejected under Section 102 over the reference to Klink.

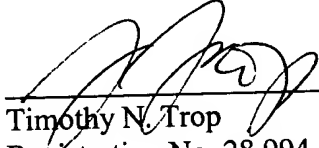
As amended, the claims call for the bond pads on both dies to be wire bonded to the same lead fingers. As shown on the cover page of the Klink patent, each of the dies 8 and 10 are bonded to different leadframe fingers. Thus, the claims as amended patentably distinguish over the art of record.

In view of these remarks, the application is now in condition for allowance and the Examiner's prompt action in accordance therewith is respectfully requested.

Respectfully submitted,

Date:

7/24/02



Timothy N. Trop
Registration No. 28,994
TROP, PRUNER & HU, P.C.
8554 Katy Freeway, Suite 100
Houston, Texas 77024
(713) 468-8880 [Phone]
(713) 468-8883 [Fax]

APPENDIX

Please amend claim 15 as follows:

15 (Three Times Amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:
stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another such that one of said dies is mounted on top of the leadframe fingers and the other of said dies is mounted on the die mounted on the leadframe fingers; and wire bonding each of said semiconductor dies to the same leadframe fingers.

Please amend claim 21 as follows:

21 (Amended). A method of connecting multiple semiconductor dies having bonding pads and a single leadframe having lead fingers, comprising:
locating a first semiconductor die on the lead fingers of the leadframe;
stacking a second semiconductor die on said first semiconductor die; and electrically connecting the bonding pads of the semiconductor dies to the same lead fingers of the leadframe.